

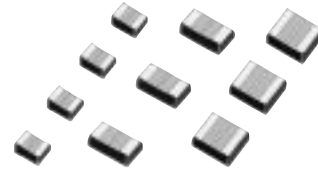
Film Chip Capacitor

Type : **ECPU(A)**

Stacked dielectric and inner electrode with simple mold - less construction

■ Features

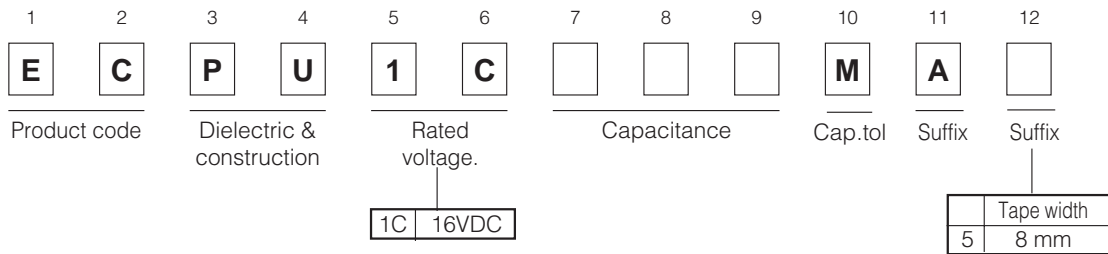
- Low ESR
- Max. capacitance values 1.0μF
- Smallest package size in film capacitors 3225/1μF
- For reflow soldering



■ Recommended Applications

- Noise suppressor
- Coupling

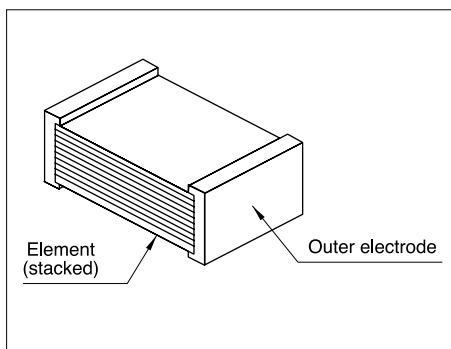
■ Explanation of Part Numbers



■ Specifications

Category temp. range (Including temperature-rise on unit surface)	- 40 to + 85°C
Rated voltage	16VDC
Capacitance range	0.1 to 1.0μF (E6)
Capacitance tolerance	± 20% (M)
Dissipation factor	1.5% max. (20°C, 1kHz)
Withstand voltage	Between terminals: Rated volt (VDC)x175% 1 to 5s
Insulation resistance	C≤0.33μF: 1000MΩ min.(20°C, 10VDC 60s) C>0.33μF: 300MΩ μFmin.(20°C, 10VDC 60s)
Soldering conditions	Reflow soldering: 240°C max. and 30 sec max. at more than 220°C (Temp. at cap. surface)

■ Construction



■ Dimensions in mm (not to scale)

Size code	L	W	H	e <sub>1</sub> e <sub>2</sub>	g
J2	2.0	1.25	1.0	0.45	≥ 0.6
H1	3.2	1.6	0.8	0.65	≥ 1.0
H2	3.2	1.6	1.0	0.65	≥ 1.0
H3	3.2	1.6	1.4	0.65	≥ 1.0
G2	3.2	2.5	1.4	0.65	≥ 1.0

\* To be applied only for size code J2

■Taping Specification for Automatic Mounting  
 Refer to the PDF file of the taping specification.

■Rating, Dimensions & Quantity/Reel

Part No.	Cap. (μF).	Dimensions (mm)				Quantity
		L	W	H	Size Code	
ECPU1C104MA5	0.1	2.0	1.25	1.0	J2	3000
ECPU1C154MA5	0.15	3.2	1.6	0.8	H1	
ECPU1C224MA5	0.22	3.2	1.6	0.8	H1	
ECPU1C334MA5	0.33	3.2	1.6	1.0	H2	
ECPU1C474MA5	0.47	3.2	1.6	1.4	H3	2000
ECPU1C684MA5	0.68	3.2	1.6	1.4	H3	
ECPU1C105MA5	1.0	3.2	2.5	1.4	G2	

■Recommended for Land Dimensions(mm)

Size Code	Land dimensions for reflow soldering		
	A	B	C
J2	0.8	2.4	1.1
H1	1.8	3.6	1.4
H2	1.8	3.6	1.4
H3	1.8	3.6	1.4
G2	1.8	3.6	2.3